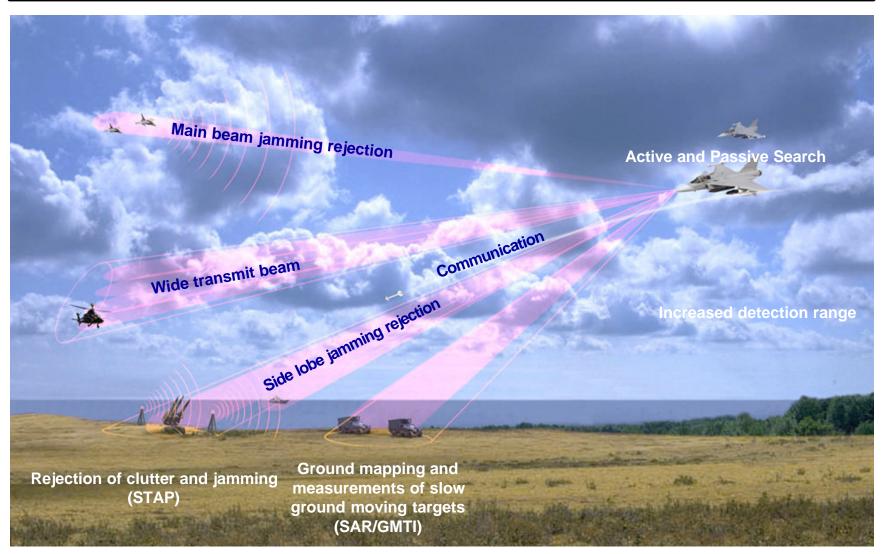


## Improved air combat awareness

- with AESA and next-generation signal processing







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**Report Documentation Page** 

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## The challenge

 The AESA performance should fit in the same "box" as today's systems, considering

- Physical size
- Power dissipation
- Physical robustness
- The High Speed Signal Processing (HSSP) project
  - A joint project between Ericsson Microwave Systems and Halmstad University, Sweden
- The goal of HSSP: "1 TFLOPS in a shoe box"

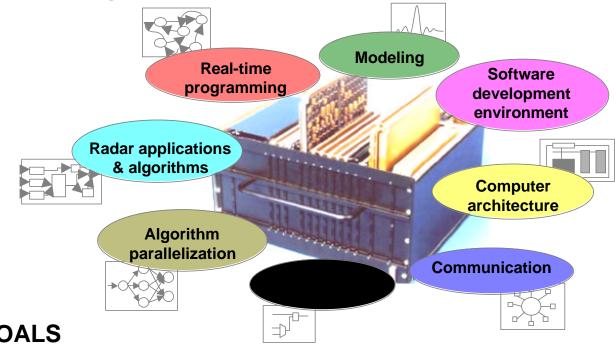




# **High Speed Signal Processing project**

#### Research for the FUTURE

 Embedded high speed signal processing computer systems for the next generation fighter aircraft radar.

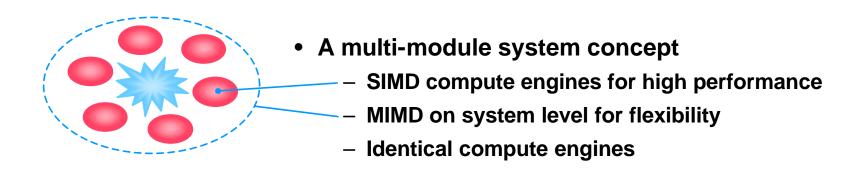


- Our GOALS
  - Strengthen our competence to ensure realization in the future
  - Find engineer efficient and economic solutions
  - Actively cooperate in a wide competence network

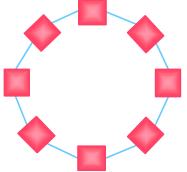




## **System realization**



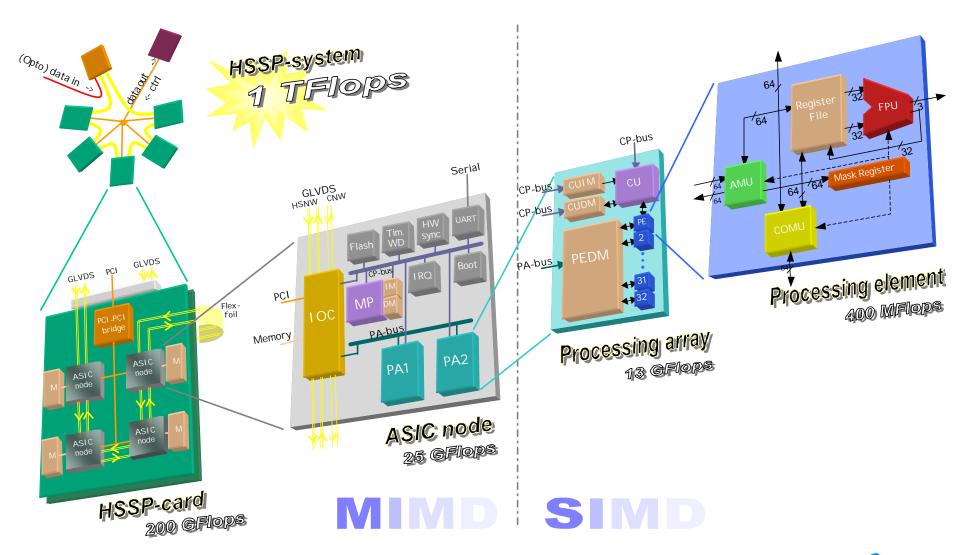
- Realizable with 0.13 mm technology (LSI Logic G13)
- The system is based on in-house SIMD based ASICs (the compute engines)
- The modules are interconnected in a ring topology by a high speed communication network (GLVDS)
- The system scales to >1 TFLOPS







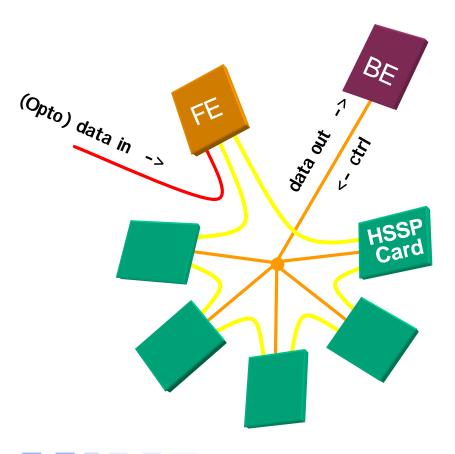
# **HSSP** system







# **HSSP** system



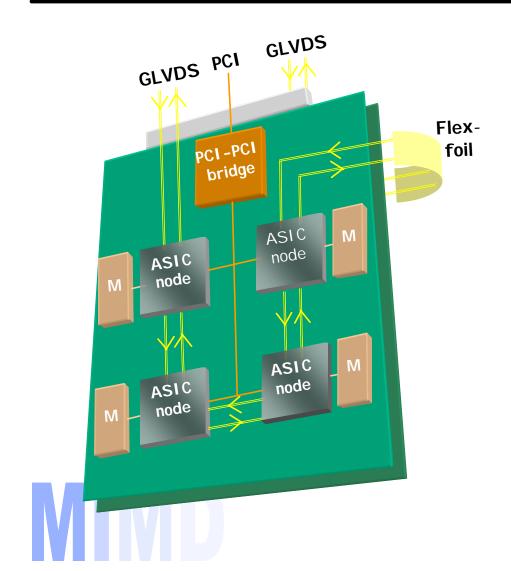
- Five HSSP cards (cassettes)
- High speed ring network
- Utility bus
- Front end (FE) with optointerface
- Back-end (BE) with utility bus interface
- Performance: >1 TFLOPS







# **HSSP** card (cassette)

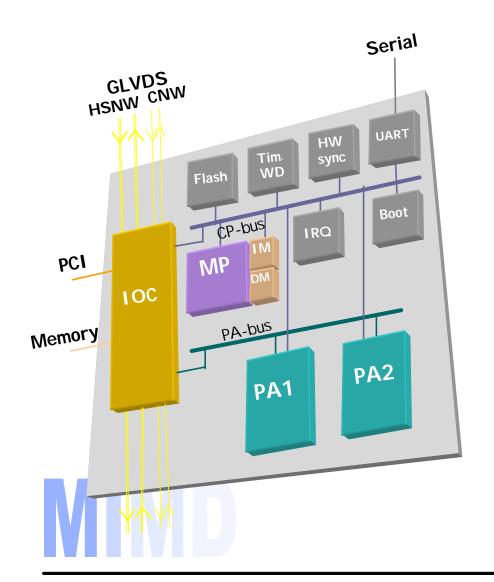


- 8 ASIC nodes per board, 4 on each side
- Double direction GLVDS ring network with separate data (1.6 GB/s) and control channel (100 MB/s)
- Utility bus
- DRAM
- Performance: 200 GFLOPS





#### **ASIC** node



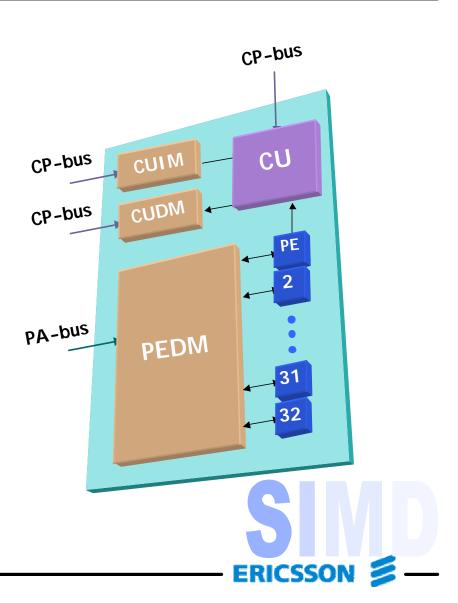
- Two processor arrays, acting as co-processors
- Master processor, IP-core running a commercial RTOS
- I/O-processor (DMA, data transformations, etc.)
- Support functions (Boot, UART, Timer, etc.)
- 0.13mm technology minimum
- Performance: 25 GFLOPS





# **Processor array (PA)**

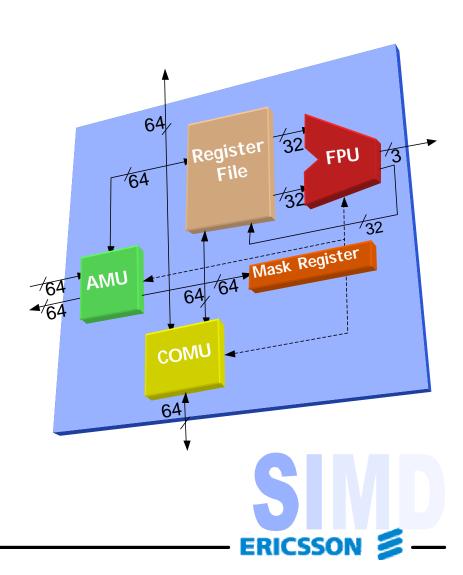
- 32 processor elements, 400 MHz, ring topology
- 32 kB memory per element
- Custom control unit w/ memory
- Performance: 12.5 GFLOPS





#### **Processor element (PE)**

- 64 32-bit registers, 4 read and 3 write ports
- 4 stage pipelined FPU, IEEE 754
- fmul, fadd, fsub, mask operations
- North/South communication interface
- 64 bit memory access, skewed load and store, 3.2
   GB/s BW
- Performance: 400 MFLOPS

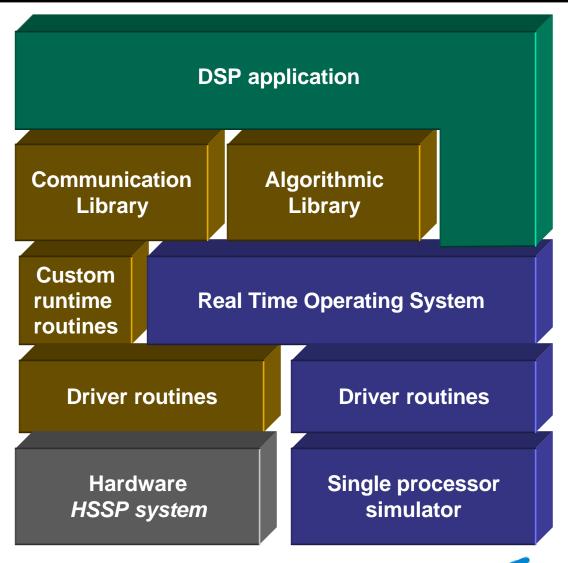




#### **Runtime environment**

- Commercial RTOS based
- Custom libraries
- Layered architecture
- In house development
- Commercial RTOS/IDE
- Hardware









#### **VLSI** test implementation

- One processor array
- Clock and control distribution
- LSI Logics G12 process (0.18 mm), standard cell
- Total area 227 mm<sup>2</sup>
  - Clearly dominated by memories
  - Memory size can however be substantially decreased
- Control unit and processor elements capable of 335 and 396 MHz, respective
- Top level design capable of 210 MHz
- Control distribution a bottle neck, can however be pipelined

